

Panel

“Avoid Being Burned!”

The risk of damage to test interfaces such as sockets, probe cards, DUT/load boards, etc. has increased significantly as the power requirement of devices continues to grow. With the explosion of mega devices - including some AI processors that regularly exceed 1000 W - the current and pin counts have grown exponentially exacerbating this issue. The challenging thermal environment also increases the potential for damage.

This panel will explore how common this damage actually is along with best practices for design and operations to avoid damage.

Join our panel of experts as they explore this “hot” topic: